

**What Is Claimed Is:**

1. A method for forming a pattern of a liquid crystal display (LCD) device, comprising:

providing a cliché having at least a first groove structure having a first width and a second groove structure having a second width equal to at least a multiple of the first width and an interval;

filling a resist material into the first and second groove structures of the cliché; and

applying the resist material filled into the first and second groove structures of the cliché onto an etching object layer of a substrate.

2. The method of claim 1, further comprising preparing a cliché including providing a cliché substrate, forming a buffer layer on the substrate, and forming the first and second groove structures by patterning the buffer layer.
3. The method of claim 2, wherein the buffer layer includes a metal layer.
4. The method of claim 2, wherein the buffer layer includes an organic layer.

5. The method of claim 1, wherein applying the resist material onto an etching object layer comprises:

contacting and rotating a printing roll onto the cliché to transfer the resist material filled in the first and second groove structures to a surface of the printing roll; and

contacting the resist material formed on the surface of the printing roll to transfer the resist material from the printing roll onto the etching object layer by rotating the printing roll.

6. The method of claim 1, wherein applying the resist material onto an etching object layer comprises:

contacting the substrate where an etching object layer is formed onto the cliché;

applying heat or pressure to the substrate; and

detaching the substrate from the cliché to transfer the resist material filled in the first and second groove structures onto the etching object layer.

7. The method of claim 1, wherein the etching object layer includes a metal layer.

8. The method of claim 1, wherein the etching object layer includes one of SiNx and SiOx.

9. The method of claim 1, wherein the etching object layer includes an organic layer.

10. The method of claim 1, wherein filling a resist material into the first and second groove structures of the cliché comprises:

depositing the resist material along an entire surface of the cliché; and  
contacting a doctor blade onto the surface of the cliché and flattening a surface of the cliché to fill the resist material into the first and second groove structures and removing the resist material that remains on the surface of the cliché.

11. A method for forming a pattern of an LCD device, comprising:

forming a buffer layer on a substrate by depositing one of an organic material and a metal material;

providing a cliché having at least first and second groove structures by patterning the buffer layer, the first groove structure having a first width and a second groove structure having a second width including a multiple of the first width and an interval;

depositing a resist material onto a surface of the cliché;

flattening the surface of the cliché using a doctor blade to fill the resist material into the first and second groove structures and removing the resist material from the surface of the cliché;

transferring the resist material filled in the first and second groove structure of the cliché onto a printing roll; and

applying the resist material formed onto the printing roll onto an etching object to form a resist pattern having a uniform thickness.

12. A method for forming a pattern of an LCD device, comprising:

forming a buffer layer on a substrate by depositing one of an organic material and a metal material;

providing a cliché having at least a first groove structure having a first width and a second groove structure having a second width equal to a multiple of the first width and an interval;

depositing a resist material on a surface of the cliché;

flattening the surface of the cliché using a doctor blade to fill the resist material into the first and second groove structures and removing the resist material that remains on the surface of the cliché;

attaching a substrate where an etching object layer is formed onto the cliché and applying at least one of heat and pressure; and

detaching the substrate from the cliché to transfer the resist material filled in the first and second groove structures of the cliché onto the etching object layer and to form a resist pattern.